
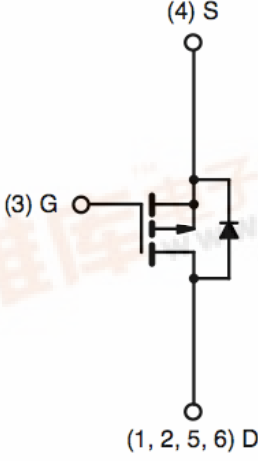
	<h1>TSM3441</h1> <h2>-20V P-Channel Enhancement-Mode MOSFET</h2>								
<p>SOT-26</p>  <p>Pin assignment: 1. Drain 6. Drain 2. Drain 5. Drain 3. Gate 4. Source</p>	<p>V_{DS} = -20V R_{DS (on)}, V_{GS} @ -4.5V, I_{DS} @ -3A = 100mΩ R_{DS (on)}, V_{GS} @ -2.5V, I_{DS} @ -2.0A = 150mΩ</p>								
<p>Features</p> <ul style="list-style-type: none"> ✧ Advanced trench process technology ✧ High density cell design for ultra low on-resistance ✧ Fully Characterized Avalanche Voltage and Current ✧ Improved Shoot-Through FOM 	<p>Block Diagram</p> <p style="text-align: center;">P-Channel MOSFET</p> 								
<p>Ordering Information</p> <table border="1" data-bbox="175 1048 758 1193"> <thead> <tr> <th>Part No.</th> <th>Packing</th> <th>Package</th> </tr> </thead> <tbody> <tr> <td>TSM3441CX6</td> <td>Tape & Reel 3,000/per reel</td> <td>SOT-26</td> </tr> </tbody> </table>	Part No.	Packing	Package	TSM3441CX6	Tape & Reel 3,000/per reel	SOT-26			
Part No.	Packing	Package							
TSM3441CX6	Tape & Reel 3,000/per reel	SOT-26							
<p>Absolute Maximum Rating (Ta = 25 °C unless otherwise noted)</p>									
<p>Parameter</p>	<p>Symbol</p>	<p>Limit</p>	<p>Unit</p>						
<p>Drain-Source Voltage</p>	<p>V_{DS}</p>	<p>-20V</p>	<p>V</p>						
<p>Gate-Source Voltage</p>	<p>V_{GS}</p>	<p>±8</p>	<p>V</p>						
<p>Continuous Drain Current,</p>	<p>I_D</p>	<p>-3</p>	<p>A</p>						
<p>Pulsed Drain Current,</p>	<p>I_{DM}</p>	<p>-10</p>	<p>A</p>						
<p>Maximum Power Dissipation</p>	<p>Ta = 25 °C</p>	<p>2</p>	<p>W</p>						
	<p>Ta = 70 °C</p>	<p>1.3</p>							
<p>Operating Junction Temperature</p>	<p>T_J</p>	<p>+150</p>	<p>°C</p>						
<p>Operating Junction and Storage Temperature Range</p>	<p>T_J, T_{STG}</p>	<p>- 55 to +150</p>	<p>°C</p>						
<p>Thermal Performance</p>									
<p>Parameter</p>	<p>Symbol</p>	<p>Limit</p>	<p>Unit</p>						
<p>Junction to Foot (Drain) Thermal Resistance</p>	<p>R_{θjf}</p>	<p>30</p>	<p>°C/W</p>						
<p>Junction to Ambient Thermal Resistance (PCB mounted)</p>	<p>R_{θja}</p>	<p>50</p>	<p>°C/W</p>						

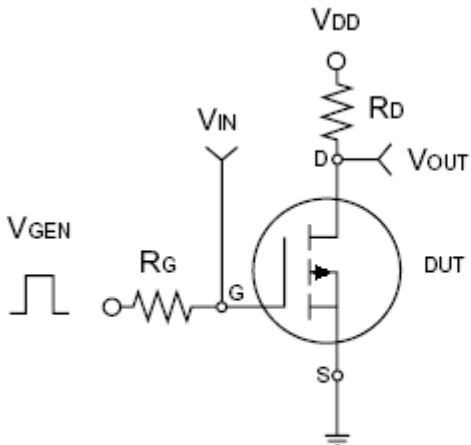
Note: Surface mounted on FR4 board t<=10sec.



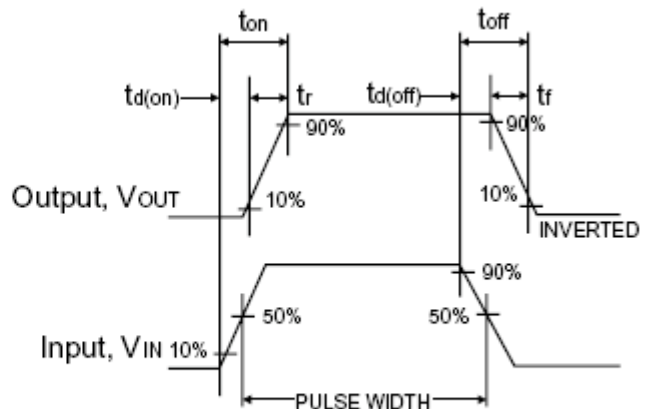


Electrical Characteristics						
(Ta = 25 °C unless otherwise noted)						
Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	BV_{DSS}	-20	--	--	V
Drain-Source On-State Resistance	$V_{GS} = -4.5V, I_D = -3A$	$R_{DS(ON)}$	--	80	100	mΩ
Drain-Source On-State Resistance	$V_{GS} = -2.5V, I_D = -2.0A$	$R_{DS(ON)}$	--	112	150	
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu A$	$V_{GS(TH)}$	-0.45	--	--	V
Zero Gate Voltage Drain Current	$V_{DS} = -16V, V_{GS} = 0V$	I_{DSS}	--	--	-1.0	μA
Gate Body Leakage	$V_{GS} = \pm 8V, V_{DS} = 0V$	I_{GSS}	--	--	±100	nA
On-State Drain Current	$V_{DS} \geq -10V, V_{GS} = -5V$	$I_{D(ON)}$	-6	--	--	A
Forward Transconductance	$V_{DS} = -5V, I_D = -3A$	g_{fs}	--	6.5	--	S
Dynamic						
Total Gate Charge	$V_{DS} = -6V, I_D = -3A,$ $V_{GS} = -4.5V$	Q_g	--	5.4	10	nC
Gate-Source Charge		Q_{gs}	--	0.8	--	
Gate-Drain Charge		Q_{gd}	--	1.1	--	
Turn-On Delay Time	$V_{DD} = -6V, R_L = 6\Omega,$ $I_D = -1A, V_{GEN} = -4.5V,$ $R_G = 6\Omega$	$t_{d(on)}$	--	5	25	nS
Turn-On Rise Time		t_r	--	19	60	
Turn-Off Delay Time		$t_{d(off)}$	--	95	110	
Turn-Off Fall Time		t_f	--	65	80	
Input Capacitance	$V_{DS} = -6V, V_{GS} = 0V,$ $f = 1.0MHz$	C_{iss}	--	447	--	pF
Output Capacitance		C_{oss}	--	127	--	
Reverse Transfer Capacitance		C_{rss}	--	80	--	
Source-Drain Diode						
Max. Diode Forward Current		I_S	--	--	-1.6	A
Diode Forward Voltage	$I_S = -1.6A, V_{GS} = 0V$	V_{SD}	--	-0.8	-1.2	V

Note : pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

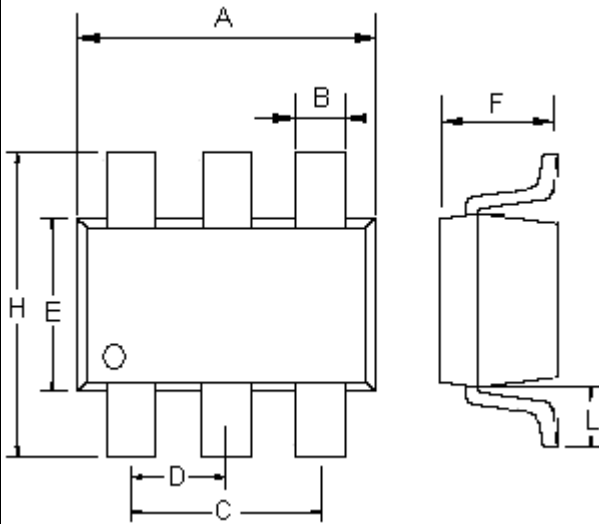


Switching Test Circuit



Switchin Waveforms

SOT-26 Mechanical Drawing



SOT-26 DIMENSION				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.70	3.00	0.106	0.118
B	0.25	0.50	0.010	0.020
C	1.90(typ)		0.075(typ)	
D	0.95(typ)		0.037(typ)	
E	1.50	1.70	0.059	0.067
F	1.05	1.35	0.041	0.053
H	2.60	3.00	0.102	0.118
L	0.60(typ)		0.024(typ)	